

TO-220-3L Plastic-Encapsulate MOSFETS

IRF730 MOSFET(N-Channel)

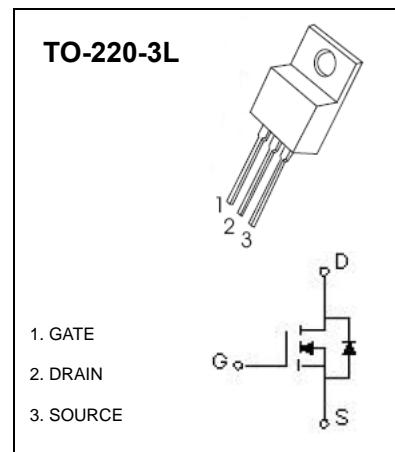
FEATURES

- Dynamic dv/dt Rating
- Repetitive Avalanche Rated
- Fast Switching
- Ease of Parallelizing
- Simple Drive Requirement

Description

Third Generation HEXFETs from Internation Rectifier provide the designer with the best combination of fast switching ,ruggedized device design,low on-resistance and cost effectiveness.

The TO-220 package is universally preferred for all commercial-industrial applications. The low thermal resistance and low package cost of the TO-220 contribute to its wide acceptance throughout the industry.



MAXIMUM RATINGS($T_a=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Units
I_D	Continuous Drain Current, $V_{GS} @ 10 \text{ V}$	5.5	A
		3.5	A
I_{DM}	Pulsed Drain Current (note 1)	22	A
P_D	Power Dissipation	2	W
V_{GS}	Gate-Sourse Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy (note 2)	290	mJ
I_{AR}	Avalanche Current (note 1)	5.5	A
E_{AR}	Repetitive Avalanche Energy (note 1)	7.4	mJ
dv/dt	Peak Diode Recovery dv/dt (note 3)	4.0	V/ns
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	62.5	$^\circ\text{C}/\text{W}$
T_J	Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature	-55~+150	$^\circ\text{C}$

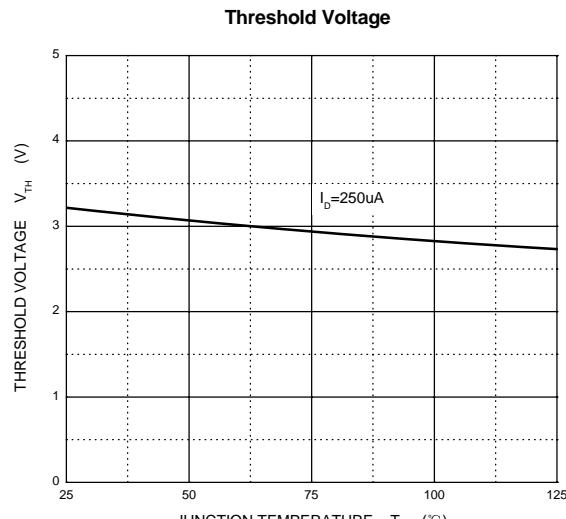
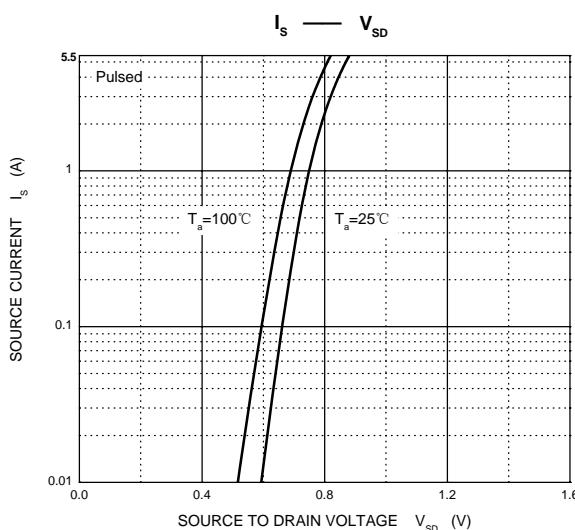
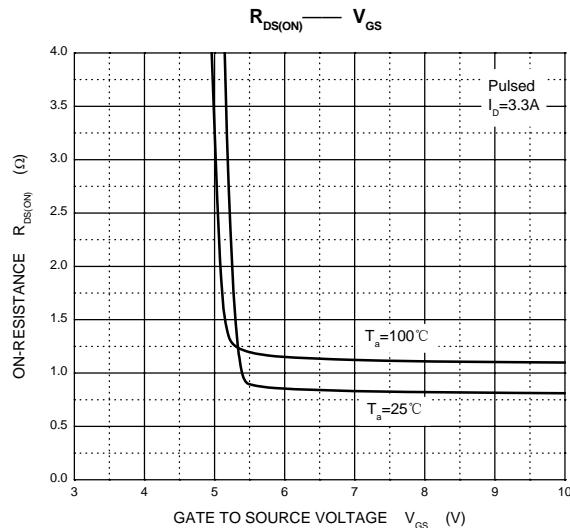
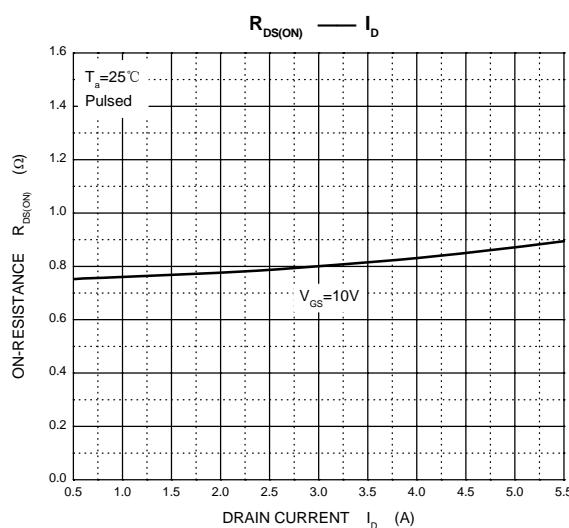
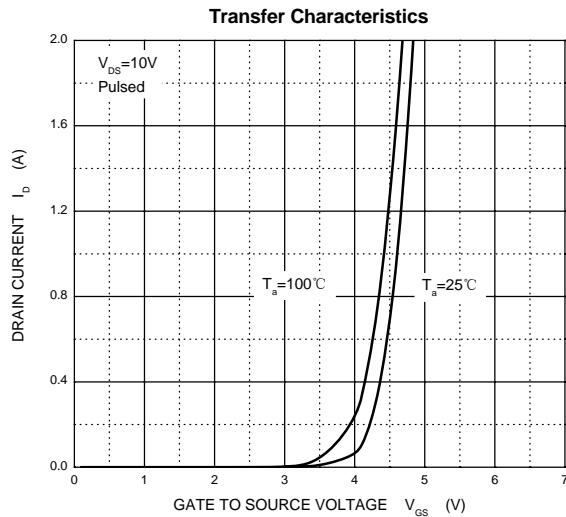
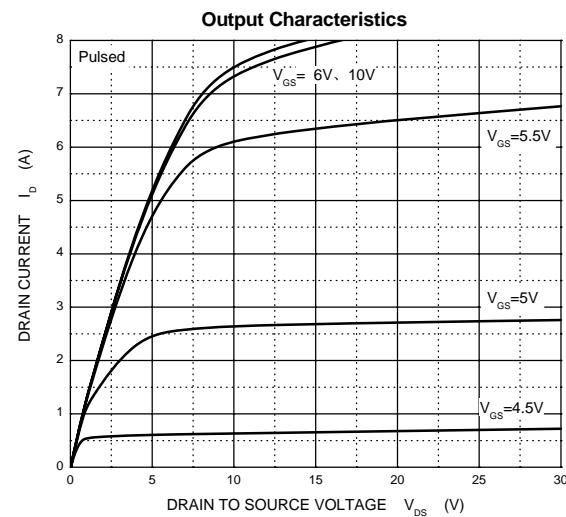
ELECTRICAL CHARACTERISTICS ($T_a=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	400			V
Gate-threshold voltage	$V_{(\text{GS})\text{th}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2		4	
Gate-body leakage	I_{GSS}	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 20\text{V}$			± 100	nA
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}}=400\text{V}, V_{\text{GS}}=0\text{V}$			25	μA
		$V_{\text{DS}}=320\text{V}, V_{\text{GS}}=0\text{V}, T_j=125^\circ\text{C}$			250	
Drain-source on-resistance (note 4)	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=3.3\text{A}$			1.0	Ω
Forward transconductance (note 4)	g_{fs}	$V_{\text{DS}}=50\text{V}, I_{\text{D}}=3.3\text{A}$	2.9			S
Diode forward voltage	V_{SD}	$I_{\text{S}}=5.5\text{A}, V_{\text{GS}}=0\text{V}$			1.6	V
Total gate charge	Q_g	$V_{\text{DS}}=320\text{V}, V_{\text{GS}}=10\text{V}, I_{\text{D}}=3.5\text{A}$			38	nC
Gate-source charge	Q_{gs}				5.7	
Gate-drain charge	Q_{gd}				22	
Input capacitance (note 5)	C_{iss}	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		700		pF
Output capacitance (note 5)	C_{oss}			170		
Reverse transfer capacitance (note 5)	C_{rss}			64		
Turn-on time(note 4 ,5)	$t_{\text{d(on)}}$	$V_{\text{DD}}=200\text{V}, R_{\text{D}}=57\Omega, I_{\text{D}}=3.5\text{A}, R_{\text{G}}=12\Omega$		10		ns
Rise tme(note 4,5)	t_r			15		
Turn-off tme(note 4,5)	$t_{\text{d(off)}}$			38		
Fall time(note 4 ,5)	t_f			14		

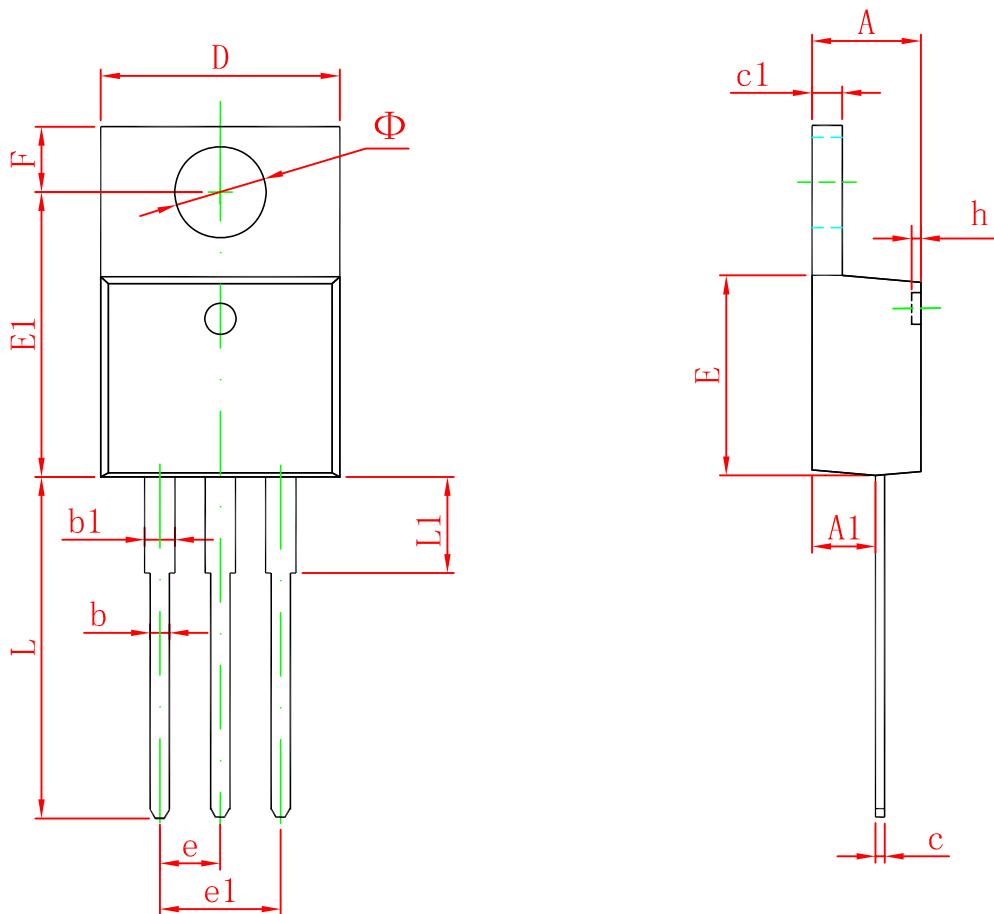
Notes:

1. Repetitive Rating ;Pulse width limited by maximum junction temperature.
2. $L=16\text{mH}, I_{\text{AS}} = 5.5\text{A}, V_{\text{DD}}=50\text{V}, R_{\text{G}}=25\Omega$, starting $T_j = 25^\circ\text{C}$.
3. $I_{\text{SD}} \leq 5.5\text{A}$, $dI/dt \leq 90\text{A}/\mu\text{s}$, $V_{\text{DD}} \leq V_{(\text{BR})\text{DSS}}$, $T_j \leq 150^\circ\text{C}$.
4. Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$.
5. These parameters have no way to verify.

Typical Characteristics IRF730



TO-220-3L Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.470	4.670	0.176	0.184
A1	2.520	2.820	0.099	0.111
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.310	0.530	0.012	0.021
c1	1.170	1.370	0.046	0.054
D	10.010	10.310	0.394	0.406
E	8.500	8.900	0.335	0.350
E1	12.060	12.460	0.475	0.491
e	2.540 TYP		0.100 TYP	
e1	4.980	5.180	0.196	0.204
F	2.590	2.890	0.102	0.114
h	0.000	0.300	0.000	0.012
L	13.400	13.800	0.528	0.543
L1	3.560	3.960	0.140	0.156
Φ	3.735	3.935	0.147	0.155